

## Trench gate field-stop IGBT, V series 600 V, 40 A very high speed

Datasheet - production data

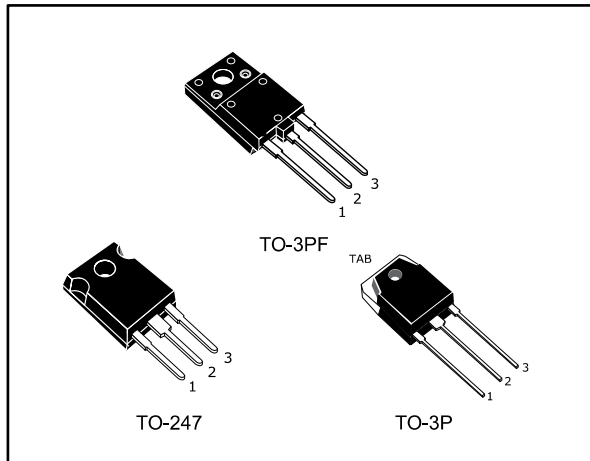
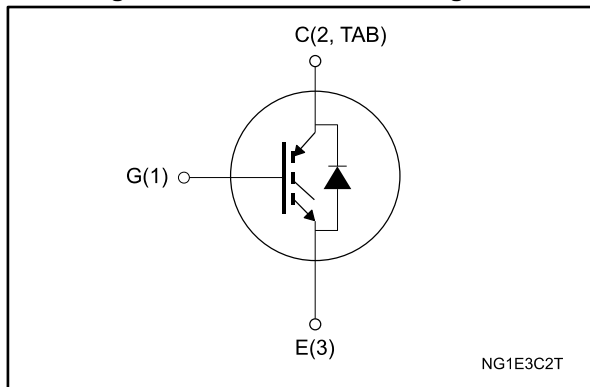


Figure 1: Internal schematic diagram



### Features

- Maximum junction temperature:  $T_J = 175\text{ }^\circ\text{C}$
- Tail-less switching off
- $V_{CE(sat)} = 1.8\text{ V (typ.) @ } I_c = 40\text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low thermal resistance
- Very fast soft recovery antiparallel diode

### Applications

- Photovoltaic inverters
- Uninterruptible power supply
- Welding
- Power factor correction
- Very high frequency converters

### Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the V series IGBTs, which represent an optimum compromise between conduction and switching losses to maximize the efficiency of very high frequency converters. Furthermore, the positive  $V_{CE(sat)}$  temperature coefficient and very tight parameter distribution result in safer paralleling operation.

Table 1: Device summary

Order code	Marking	Package	Packing
STGFW40V60DF	GFW40V60DF	TO-3PF	Tube
STGW40V60DF	GW40V60DF	TO-247	Tube
STGWT40V60DF	GWT40V60DF	TO-3P	Tube

## Contents

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value		Unit
		TO-247 TO-3P	TO-3PF	
V <sub>CES</sub>	Collector-emitter voltage (V <sub>GE</sub> = 0 V)	600		V
I <sub>C</sub>	Continuous collector current at T <sub>C</sub> = 25 °C	80		A
	Continuous collector current at T <sub>C</sub> = 100 °C	40		A
I <sub>CP</sub> <sup>(1)</sup>	Pulsed collector current	160		A
V <sub>GE</sub>	Gate-emitter voltage	±20		V
I <sub>F</sub>	Continuous forward current at T <sub>C</sub> = 25 °C	80		A
	Continuous forward current at T <sub>C</sub> = 100 °C	40		A
I <sub>FP</sub> <sup>(1)</sup>	Pulsed forward current	160		A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	283	62.5	W
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s, T <sub>C</sub> = 25 °C)	3.5		kV
T <sub>STG</sub>	Storage temperature range	-55 to 150		°C
T <sub>J</sub>	Operating junction temperature range	-55 to 175		°C

**Notes:**

<sup>(1)</sup>Pulse width is limited by maximum junction temperature.

Table 3: Thermal data

Symbol	Parameter	Value		Unit
		TO-247 TO-3P	TO-3PF	
R <sub>thJC</sub>	Thermal resistance junction-case IGBT	0.53	2.4	°C/W
R <sub>thJC</sub>	Thermal resistance junction-case diode	1.14	2.6	°C/W
R <sub>thJA</sub>	Thermal resistance junction-ambient	50		°C/W

## 2 Electrical characteristics

$T_J = 25\text{ °C}$  unless otherwise specified

**Table 4: Static characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)CES}$	Collector-emitter breakdown voltage	$V_{GE} = 0\text{ V}$ , $I_C = 2\text{ mA}$	600			V
$V_{CE(sat)}$	Collector-emitter saturation voltage	$V_{GE} = 15\text{ V}$ , $I_C = 40\text{ A}$		1.8	2.3	V
		$V_{GE} = 15\text{ V}$ , $I_C = 40\text{ A}$ , $T_J = 125\text{ °C}$		2.15		
		$V_{GE} = 15\text{ V}$ , $I_C = 40\text{ A}$ , $T_J = 175\text{ °C}$		2.35		
$V_F$	Forward on-voltage	$I_F = 40\text{ A}$		1.7	2.45	V
		$I_F = 40\text{ A}$ , $T_J = 125\text{ °C}$		1.4		
		$I_F = 40\text{ A}$ , $T_J = 175\text{ °C}$		1.3		
$V_{GE(th)}$	Gate threshold voltage	$V_{CE} = V_{GE}$ , $I_C = 1\text{ mA}$	5	6	7	V
$I_{CES}$	Collector cut-off current	$V_{GE} = 0\text{ V}$ , $V_{CE} = 0\text{ V}$			25	$\mu\text{A}$
$I_{GES}$	Gate-emitter leakage current	$V_{CE} = 0\text{ V}$ , $V_{GE} = \pm 20\text{ V}$			$\pm 250$	nA

**Table 5: Dynamic characteristics**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{ies}$	Input capacitance	$V_{CE} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GE} = 0\text{ V}$	-	5400	-	pF
$C_{oes}$	Output capacitance		-	220	-	pF
$C_{res}$	Reverse transfer capacitance		-	180	-	pF
$Q_g$	Total gate charge	$V_{CC} = 480\text{ V}$ , $I_C = 40\text{ A}$ , $V_{GE} = 0\text{ to }15\text{ V}$ (see <a href="#">Figure 35: "Gate charge test circuit"</a> )	-	226	-	nC
$Q_{ge}$	Gate-emitter charge		-	38	-	nC
$Q_{gc}$	Gate-collector charge		-	95	-	nC

Table 6: IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 40\text{ A}$ , $R_G = 10\ \Omega$ , $V_{GE} = 15\text{ V}$ (see <a href="#">Figure 34: "Test circuit for inductive load switching"</a> )	-	52	-	ns
$t_r$	Current rise time		-	17	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1850	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off delay time		-	208	-	ns
$t_f$	Current fall time		-	20	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	456	-	$\mu$ J
$E_{off}^{(2)}$	Turn-off switching energy		-	411	-	$\mu$ J
$E_{ts}$	Total switching energy		-	867	-	$\mu$ J
$t_{d(on)}$	Turn-on delay time	$V_{CE} = 400\text{ V}$ , $I_C = 40\text{ A}$ , $R_G = 10\ \Omega$ , $V_{GE} = 15\text{ V}$ , $T_J = 175\text{ }^\circ\text{C}$ (see <a href="#">Figure 34: "Test circuit for inductive load switching"</a> )	-	52	-	ns
$t_r$	Current rise time		-	21	-	ns
$(di/dt)_{on}$	Turn-on current slope		-	1538	-	A/ $\mu$ s
$t_{d(off)}$	Turn-off-delay time		-	220	-	ns
$t_f$	Current fall time		-	21	-	ns
$E_{on}^{(1)}$	Turn-on switching energy		-	1330	-	$\mu$ J
$E_{off}^{(2)}$	Turn-off switching energy		-	560	-	$\mu$ J
$E_{ts}$	Total switching energy		-	1890	-	$\mu$ J

**Notes:**

(1)Including the reverse recovery of the diode.

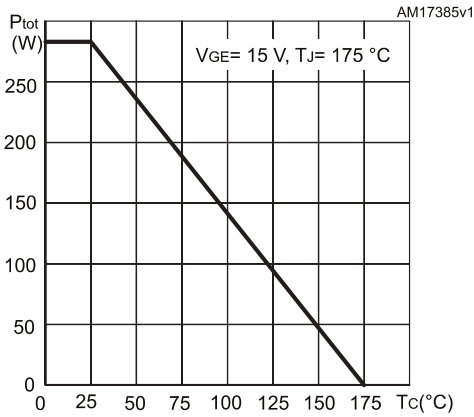
(2)Including the tail of the collector current.

Table 7: Diode switching characteristics (inductive load)

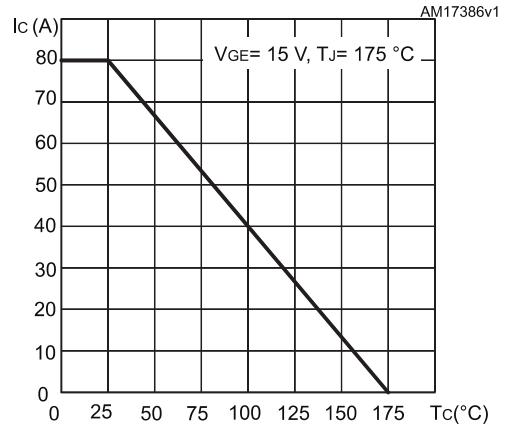
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 40\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ (see <a href="#">Figure 34: "Test circuit for inductive load switching"</a> )	-	41	-	ns
$Q_{rr}$	Reverse recovery charge		-	440	-	nC
$I_{rrm}$	Reverse recovery current		-	21.6	-	A
$dl_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$		-	1363	-	A/ $\mu$ s
$E_{rr}$	Reverse recovery energy		-	151	-	$\mu$ J
$t_{rr}$	Reverse recovery time	$I_F = 40\text{ A}$ , $V_R = 400\text{ V}$ , $V_{GE} = 15\text{ V}$ , $di/dt = 1000\text{ A}/\mu\text{s}$ , $T_J = 175\text{ }^\circ\text{C}$ (see <a href="#">Figure 34: "Test circuit for inductive load switching"</a> )	-	109	-	ns
$Q_{rr}$	Reverse recovery charge		-	2400	-	nC
$I_{rrm}$	Reverse recovery current		-	44.4	-	A
$dl_{rr}/dt$	Peak rate of fall of reverse recovery current during $t_b$		-	670	-	A/ $\mu$ s
$E_{rr}$	Reverse recovery energy		-	718	-	$\mu$ J

## 2.1 Electrical characteristics curves

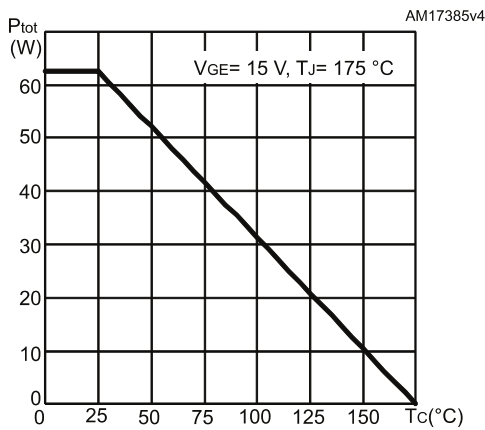
**Figure 2: Power dissipation vs case temperature for TO-247 and TO-3P**



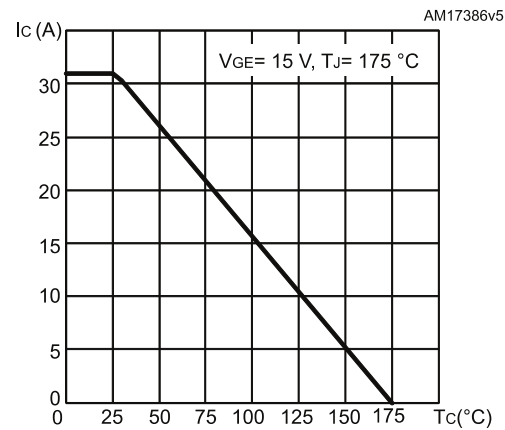
**Figure 3: Collector current vs case temperature for TO-247 and TO-3P**



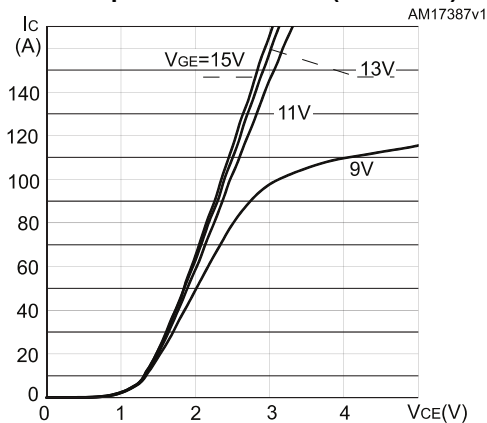
**Figure 4: Power dissipation vs case temperature for TO-3PF**



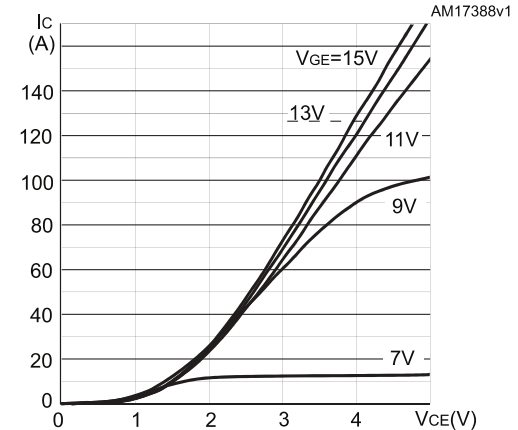
**Figure 5: Collector current vs case temperature for TO-3PF**

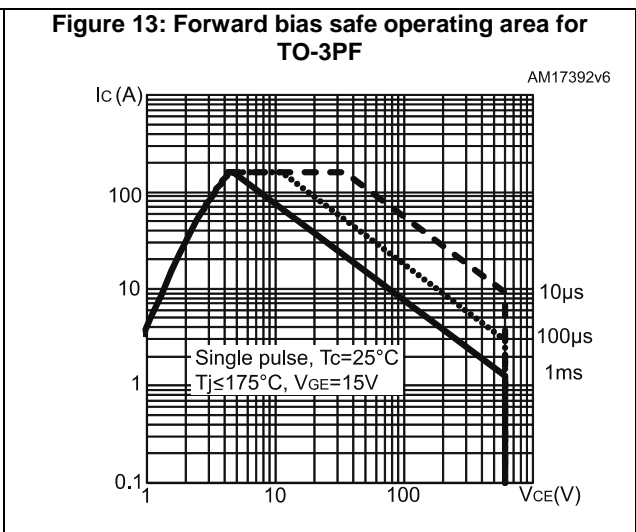
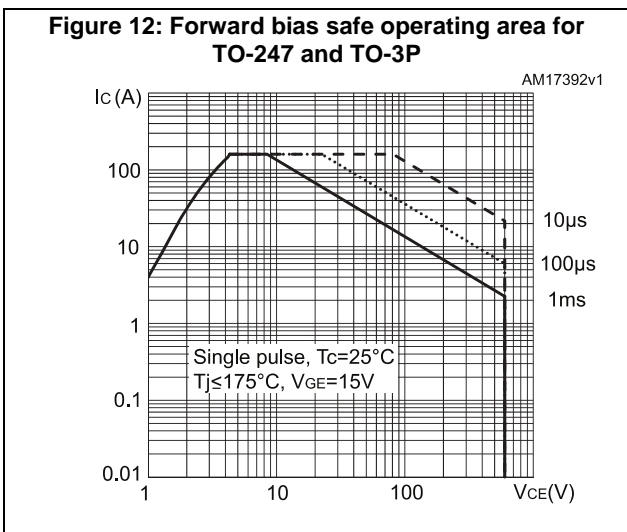
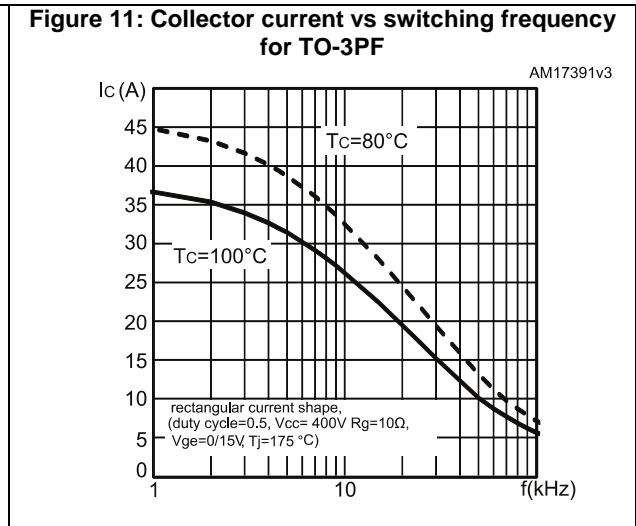
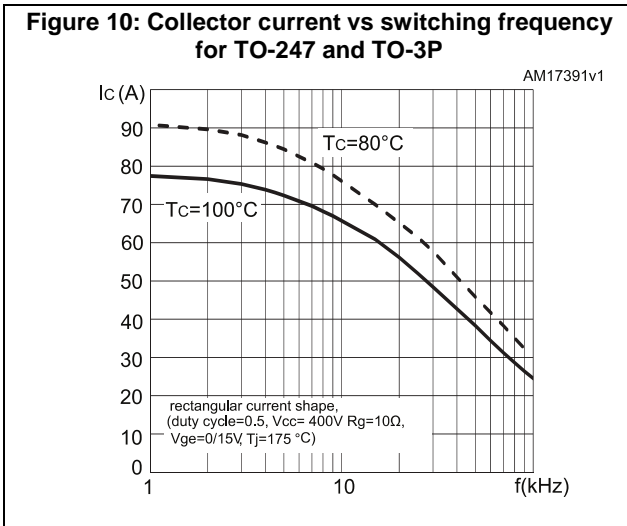
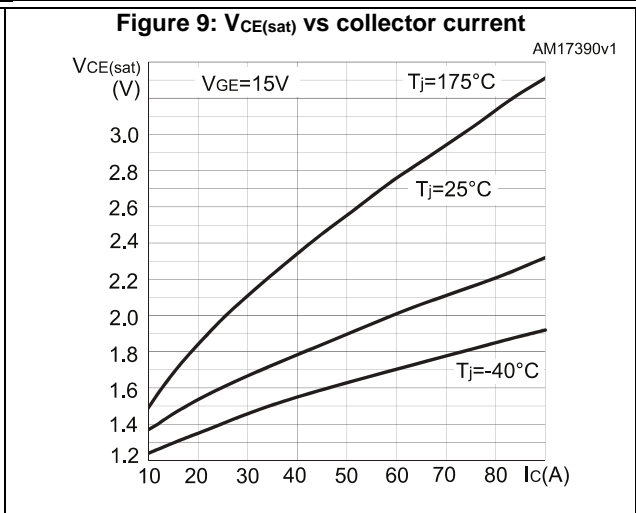
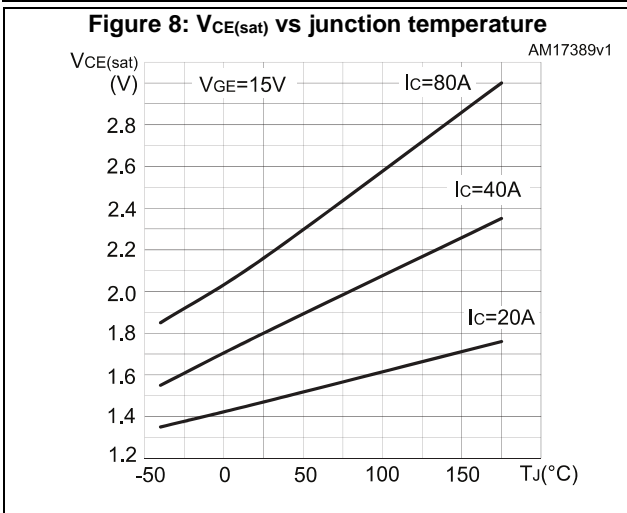


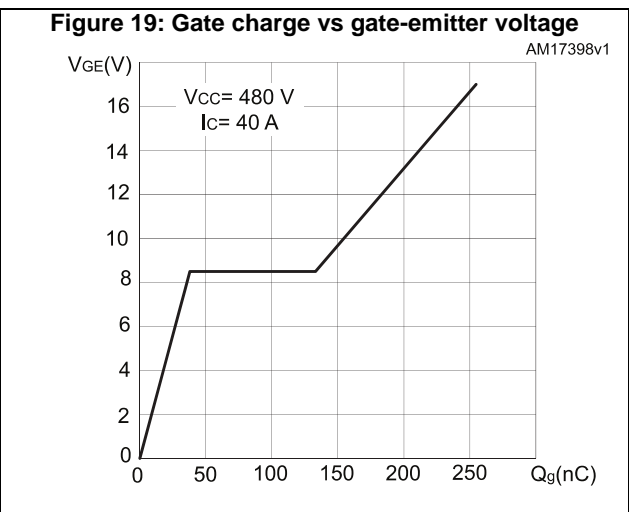
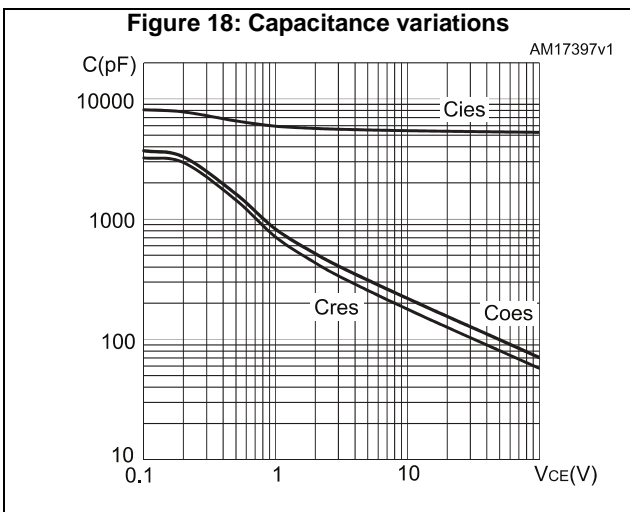
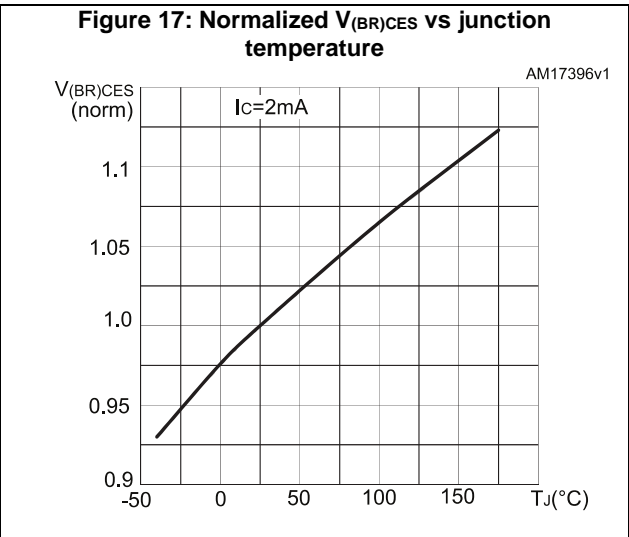
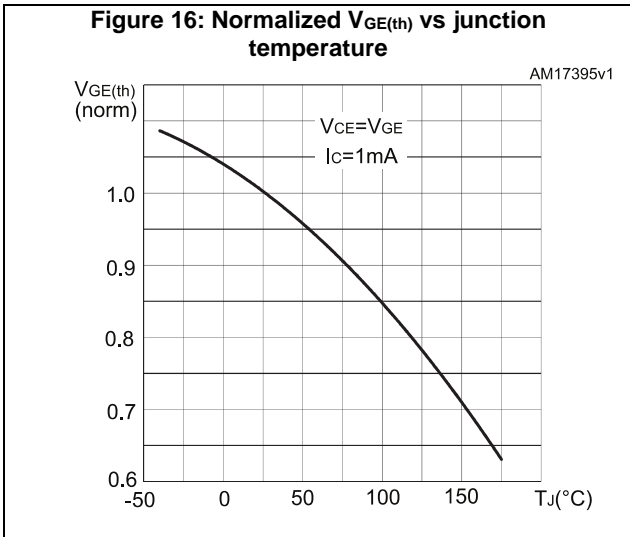
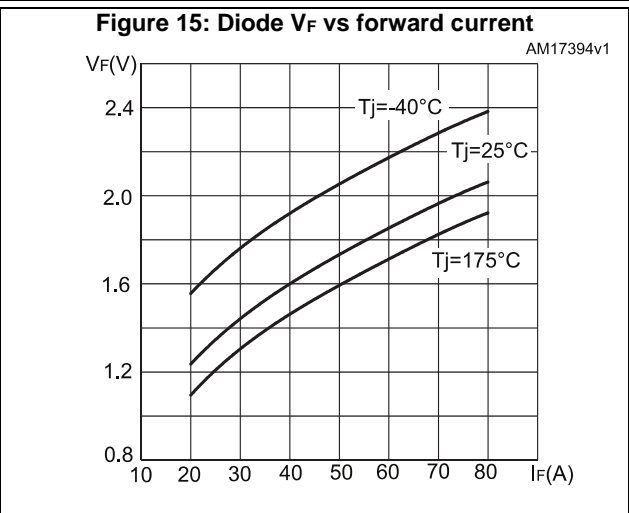
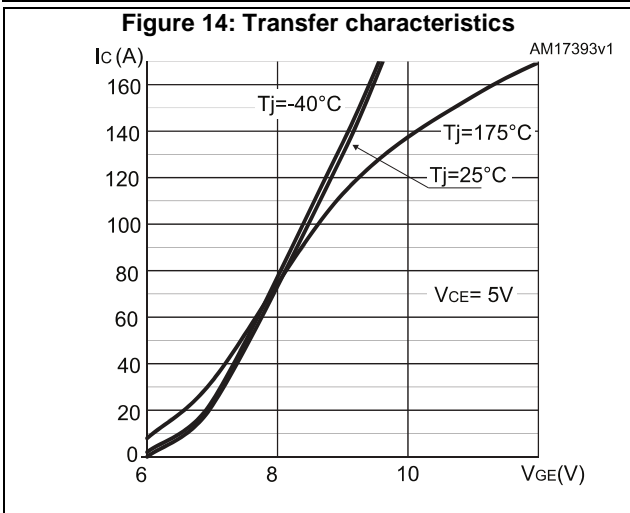
**Figure 6: Output characteristics (T<sub>J</sub> = 25 °C)**



**Figure 7: Output characteristics (T<sub>J</sub> = 175 °C)**









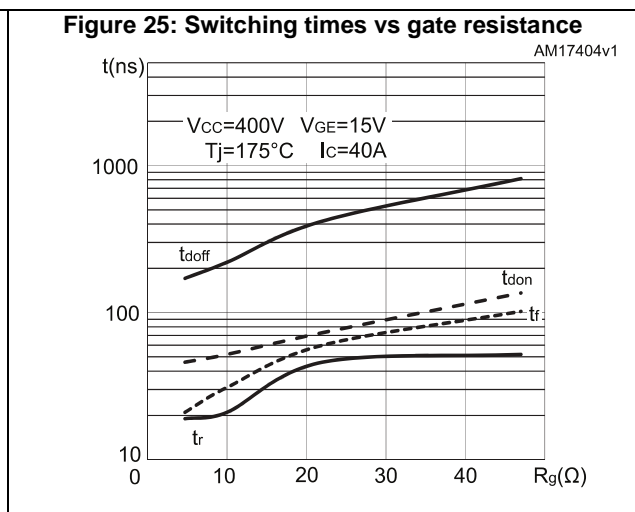
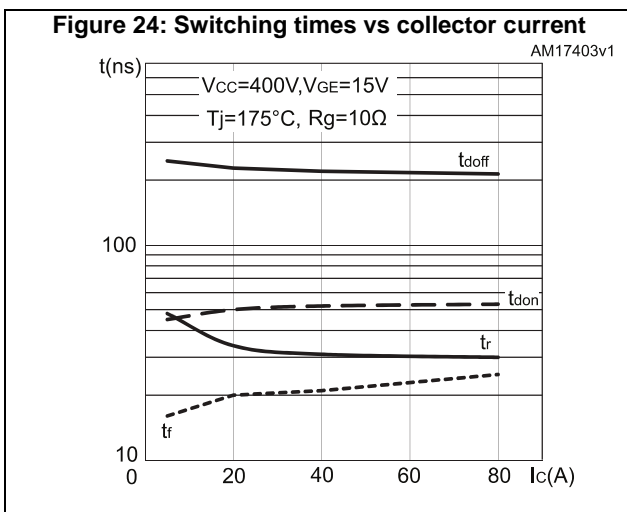
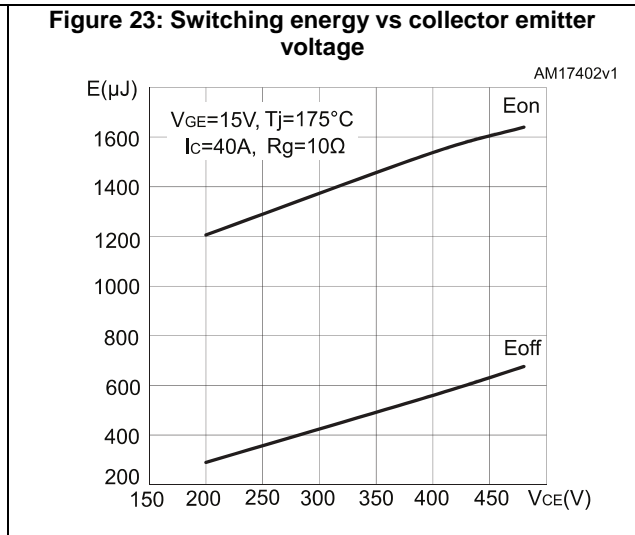
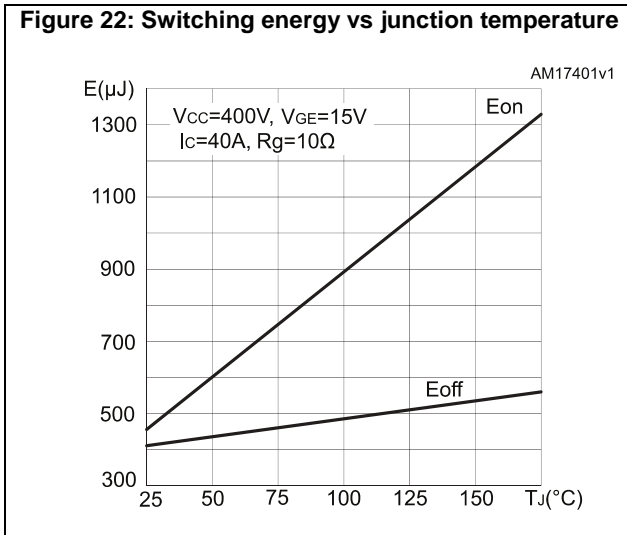
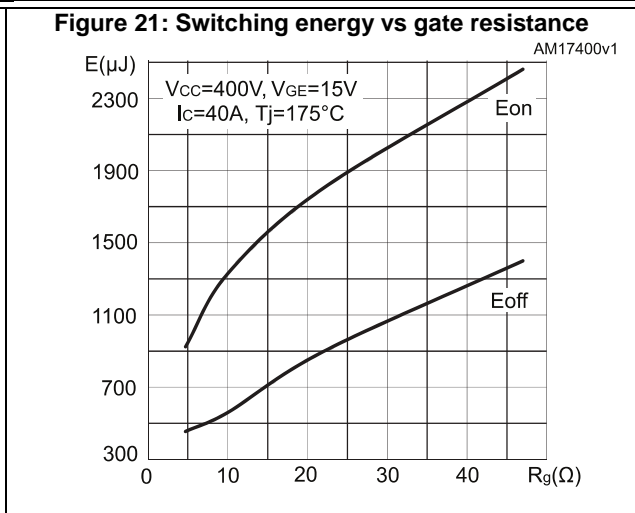
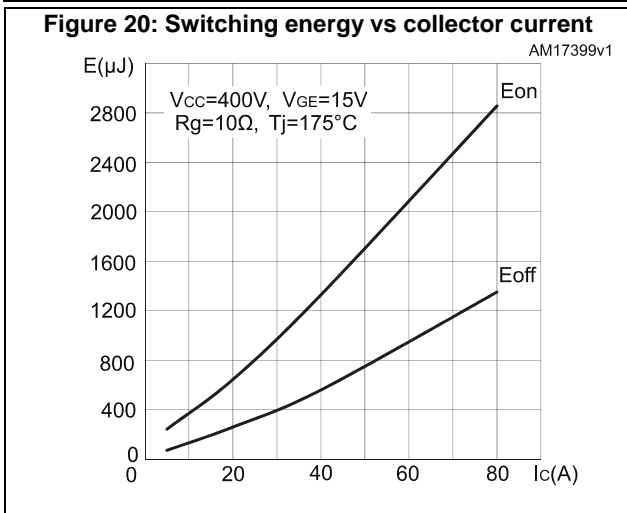


Figure 26: Reverse recovery current vs diode current slope

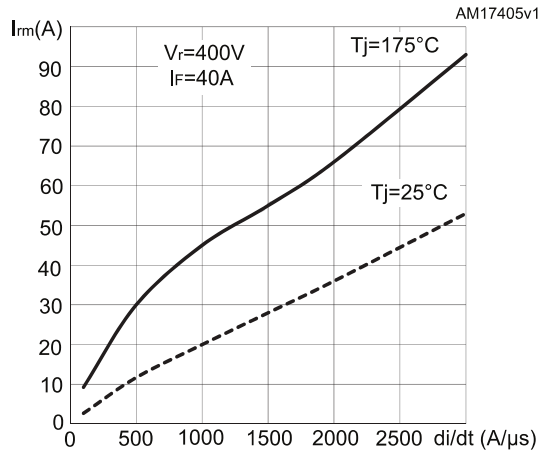


Figure 27: Reverse recovery time vs diode current slope

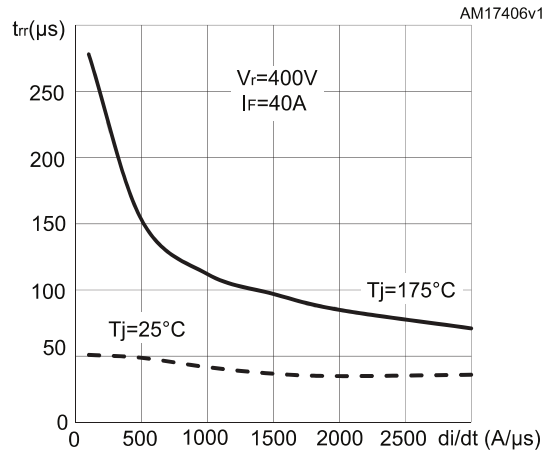


Figure 28: Reverse recovery charge vs diode current slope

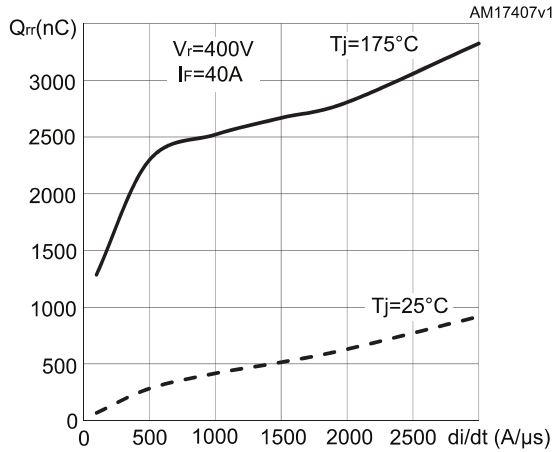


Figure 29: Reverse recovery energy vs diode current slope

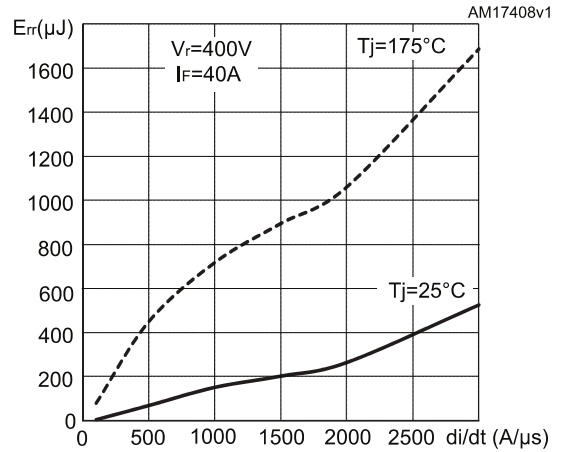


Figure 30: Thermal impedance for IGBT in TO-247 and TO-3P

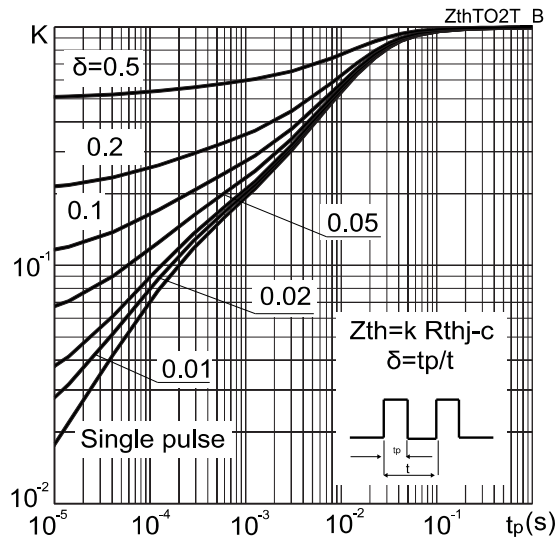


Figure 31: Thermal impedance for IGBT in TO-3PF

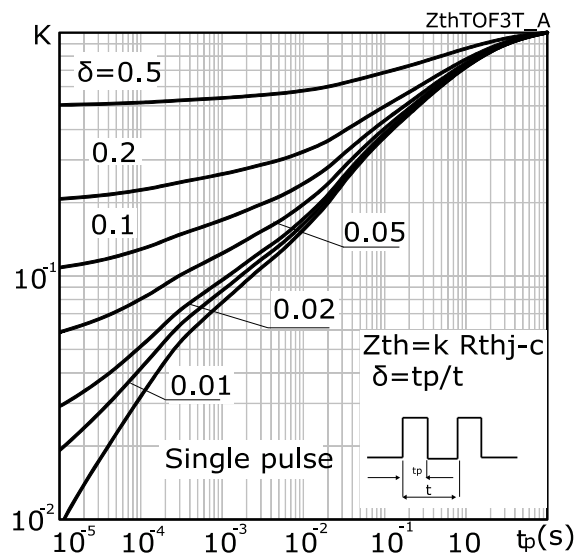


Figure 32: Thermal impedance for diode in TO-247 and TO-3P

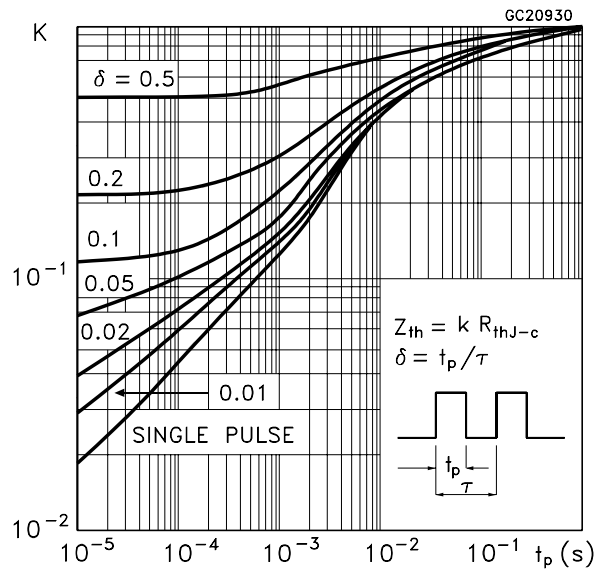
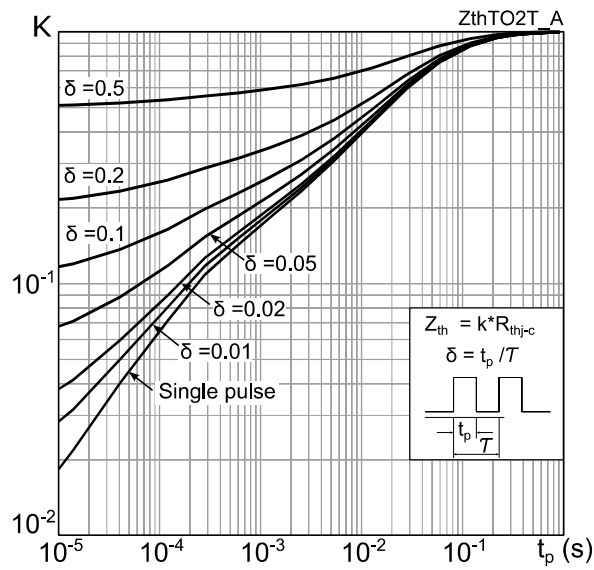
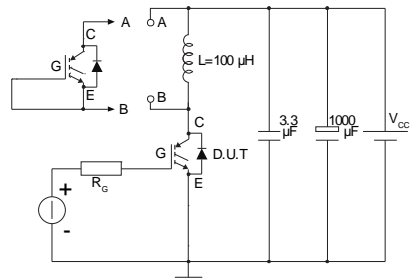


Figure 33: Thermal impedance for diode in TO-3PF



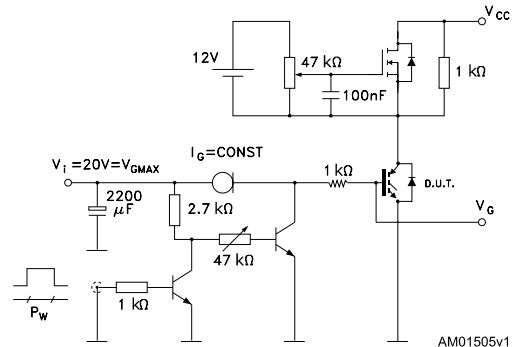
### 3 Test circuits

Figure 34: Test circuit for inductive load switching



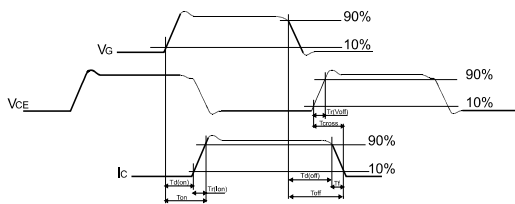
AM01504v1

Figure 35: Gate charge test circuit



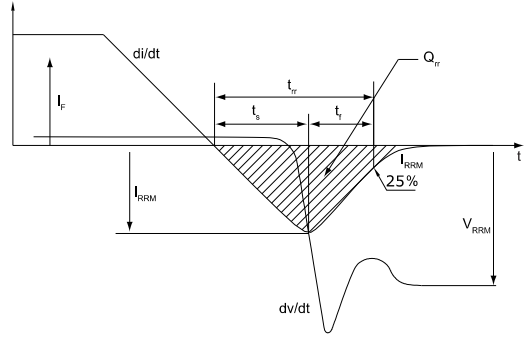
AM01505v1

Figure 36: Switching waveform



AM01506v1

Figure 37: Diode reverse recovery waveform



AM01507v1

## 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO-3PF package information

Figure 38: TO-3PF package outline

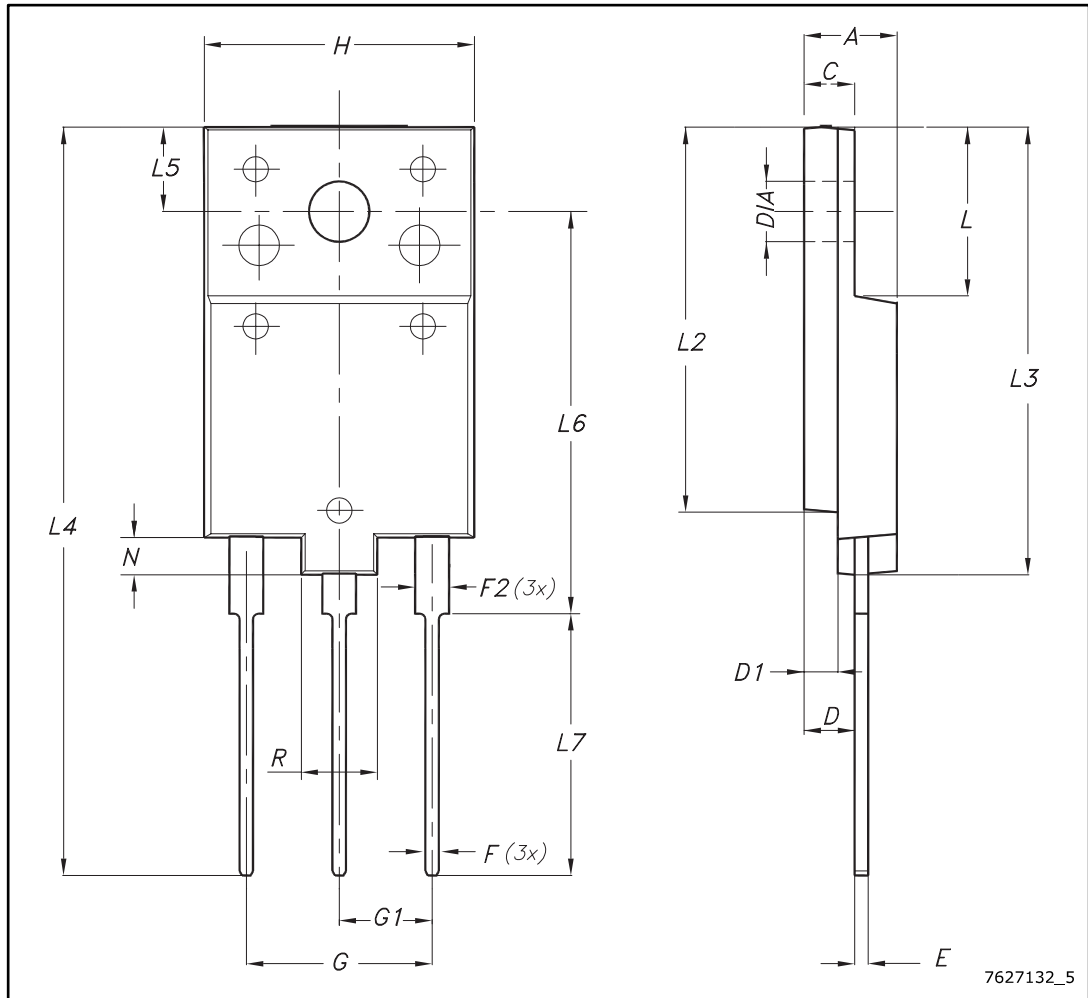


Table 8: TO-3PF mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.10
F	0.65		0.95
F2	1.80		2.20
G	10.30		11.50
G1		5.45	
H	15.30		15.70
L	9.80	10	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.20		44.40
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

### 4.2 TO-247 package information

Figure 39: TO-247 package outline

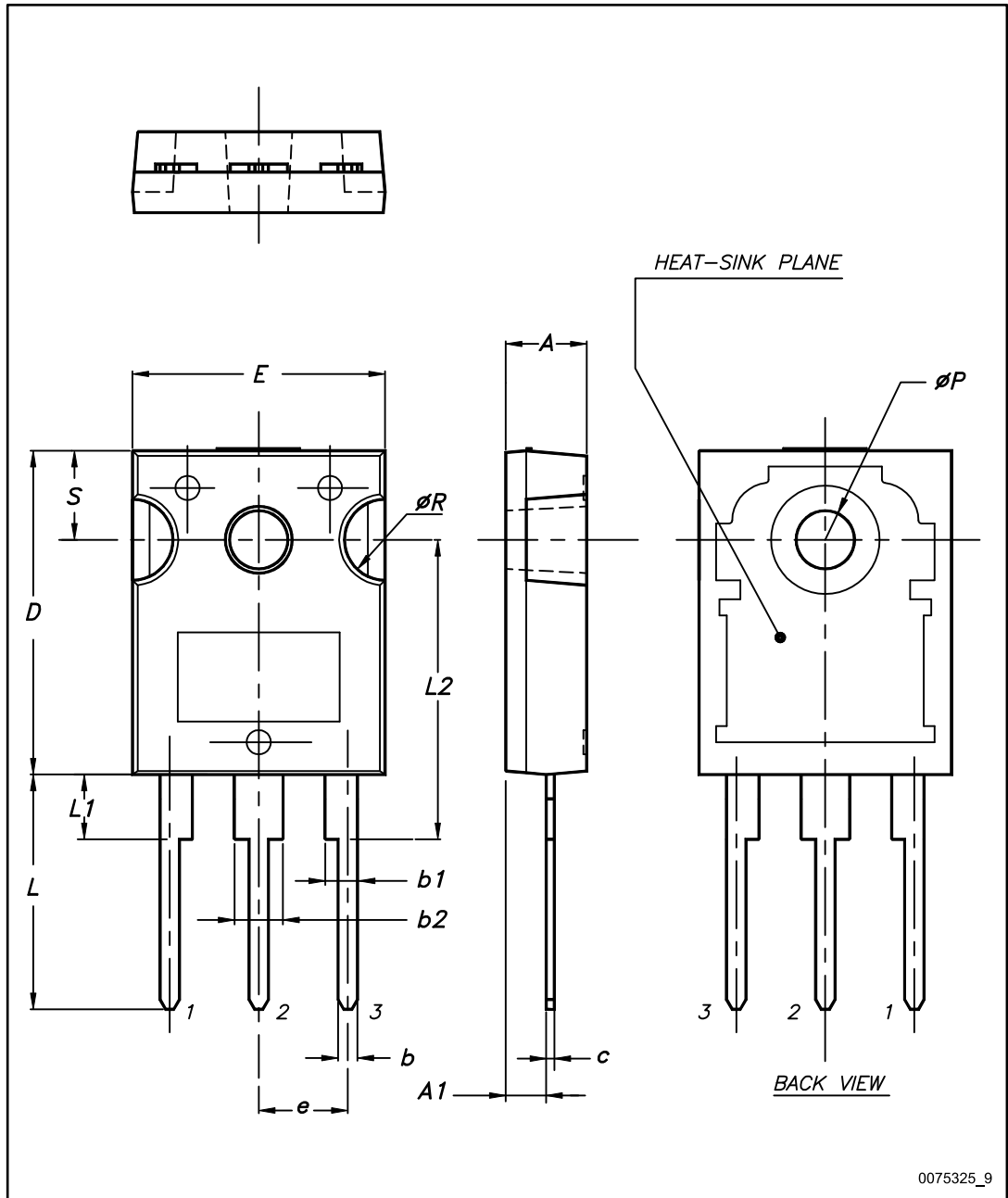




Table 9: TO-247 package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

### 4.3 TO-3P package information

Figure 40: TO-3P package outline



8045950\_2

Table 10: TO-3P package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60	4.80	5.00
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1.00	1.20
b1	1.80	2.00	2.20
b2	2.80	3.00	3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1	13.70	13.90	14.10
E	15.40	15.60	15.80
E1	13.40	13.60	13.80
E2	9.40	9.60	9.90
e	5.15	5.45	5.75
L	19.80	20.00	20.20
L1	3.30	3.50	3.70
L2	18.20	18.40	18.60
ØP	3.30	3.40	3.50
ØP1	3.10	3.20	3.30
Q	4.80	5.00	5.20
Q1	3.60	3.80	4

## 5 Revision history

Table 11: Document revision history

Date	Revision	Changes
20-Mar-2013	1	Initial release
17-Apr-2013	2	Document status promoted from preliminary data to production data. Added: <i>Section 2.1: Electrical characteristics (curves)</i>
04-Jun-2013	3	Added minimum and maximum values for $V_{GE(th)}$ in <i>Table 4: Static characteristics</i> .
11-Sep-2013	4	Updated $V_F$ value in <i>Table 4: Static characteristics</i> .
08-Oct-2013	5	Updated title, features and description in cover page.
10-Jan-2014	6	Updated <i>Figure 8: <math>V_{CE(sat)}</math> vs. junction temperature</i> , <i>Figure 15: Diode <math>V_F</math> vs. forward current</i> and <i>Figure 16: Normalized <math>V_{GE(th)}</math> vs junction temperature</i> .
03-Mar-2014	7	Updated test conditions in <i>Table 7: Diode switching characteristics (inductive load)</i> .
23-Apr-2014	8	Added new device in TO-3PF. Updated <i>Table 1: Device summary</i> , <i>Table 2: Absolute maximum ratings</i> , <i>Table 3: Thermal data</i> and <i>Section 4: Package mechanical data</i> . Added <i>Figure 4: Power dissipation vs. case temperature for TO-3PF</i> , <i>Figure 5: Collector current vs. case temperature for TO-3PF</i> , <i>Figure 11: Collector current vs. switching frequency for TO-3PF</i> and <i>Figure 12: Forward bias safe operating area for TO-247 and TO-3P</i> . Minor text changes.
27-Oct-2017	9	Updated <i>Table 3: "Thermal data"</i> . Added <i>Figure 33: "Thermal impedance for diode in TO-3PF"</i> . Updated <i>Section 4: "Package information"</i> . Minor text changes

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### Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: [info@moschip.ru](mailto:info@moschip.ru)

Skype отдела продаж:

moschip.ru

moschip.ru\_4

moschip.ru\_6

moschip.ru\_9